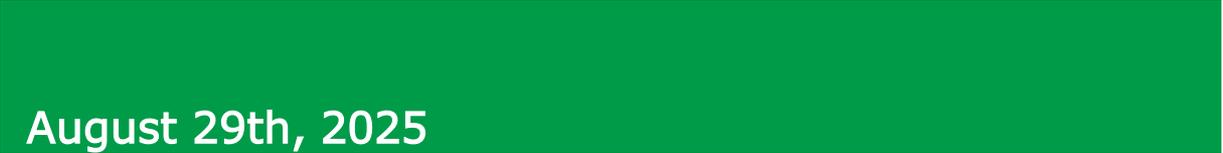




1H, 2025 Investor Conference

尼得科超眾科技股份有限公司
Nidec Chaun-Choung Technology Corp.



August 29th, 2025

Disclaimer

This presentation of NCCI contains forward-looking statements subject to risks and uncertainties. Actual results may differ materially from the contained in the forward-looking statements.

The forward-looking statements in this presentation are the current belief of NCCI as of the date for this release, and NCCI has no obligation to update the forward-looking statements for new information, future events, or otherwise.

- **Company Profile**
- **Focus: Market, Products & Technologies**
- **1H, 2025 Financial Results**
- **Q & A**

Company Profile

- **Chairman and CEO** : Miyoshi Akihiro
- **Founded** : Dec.14. 1973
- **Stock Listing** : TWSE (ticker: 6230)
- **Nidec Corporation:**
Hold 86.30% shares, as a major shareholder (Jul. 2025).
- **Capital** : NT\$ 863,434 (K)
- **HQ Address** : No. 184-3, Zhongxing N. St., Sanchong Dist.,
New Taipei City 241, Taiwan
- **Main Business** : Heat Sink & Thermal Solutions
- **WW Factories & Offices**



Worldwide Factories & Offices





PROFESSIONAL
THERMAL TECHNOLOGY
TEAM & CONTINUOUS
INNOVATION

MARKET-
ORIENTED PRODUCT
PORTFOLIO &
CUSTOMIZATION
CAPABILITY

MANUFACTURING
& TESTING PROCESS
INTEGRATION
ADVANTAGE

GROUP
RESOURCE
INTEGRATION
& GLOBAL
DEPLOYMENT

1

Professional Thermal Team & Innovation

Our team has expertise in thermal design, material development, and process optimization.

We develop Heat Pipes, Vapor Chambers, 3D VCs, ultra-thin pipes, and liquid cooling modules.

We work with global customers to address AI and HPC thermal challenges.

2

Group Resource Integration & Global Deployment

We co-develop fans and liquid cooling components with Nidec Group.

We have manufacturing bases in Taiwan, Kunshan, and Chongqing.

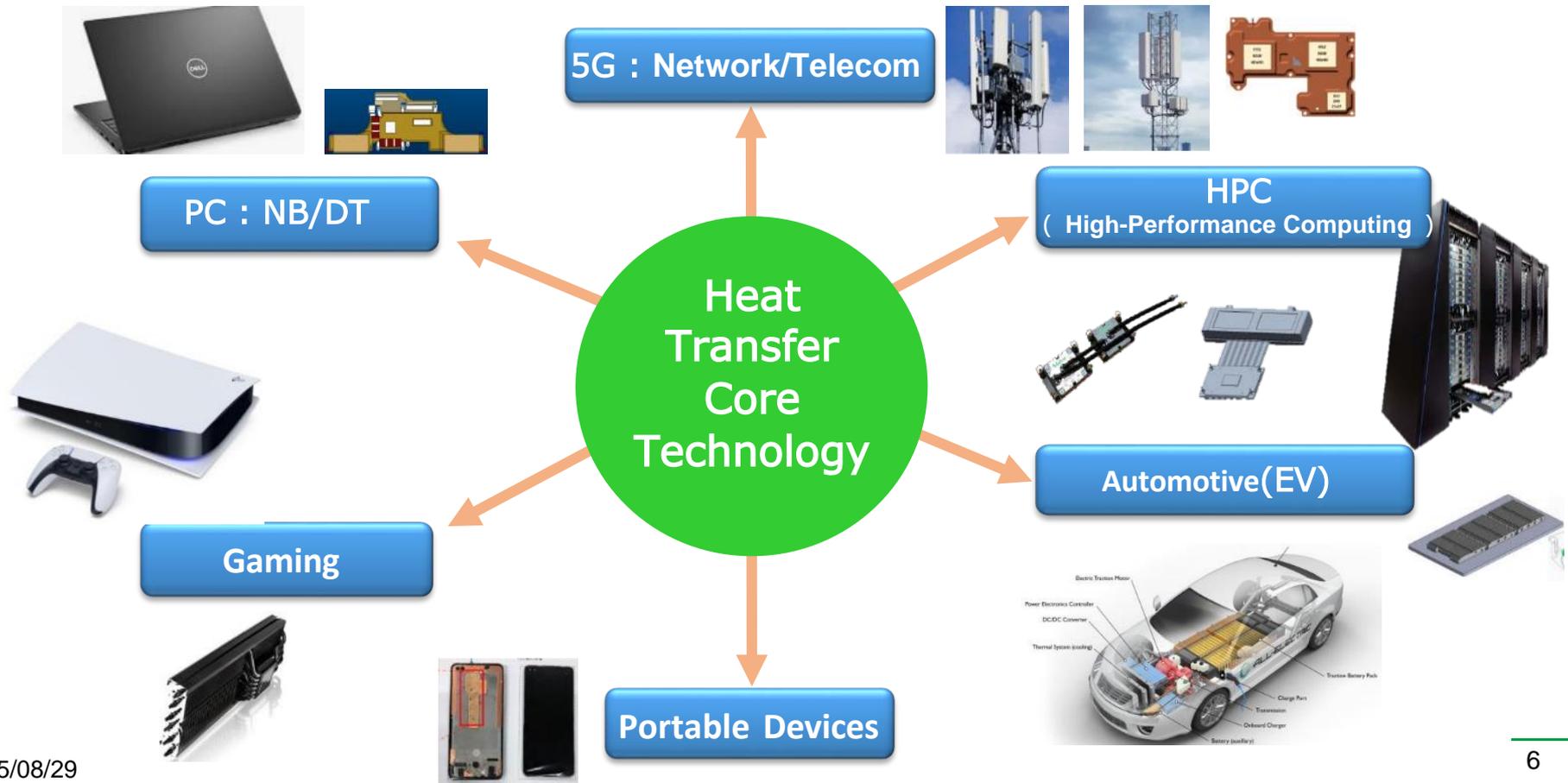
We provide large-scale production with complete process and testing capabilities

3

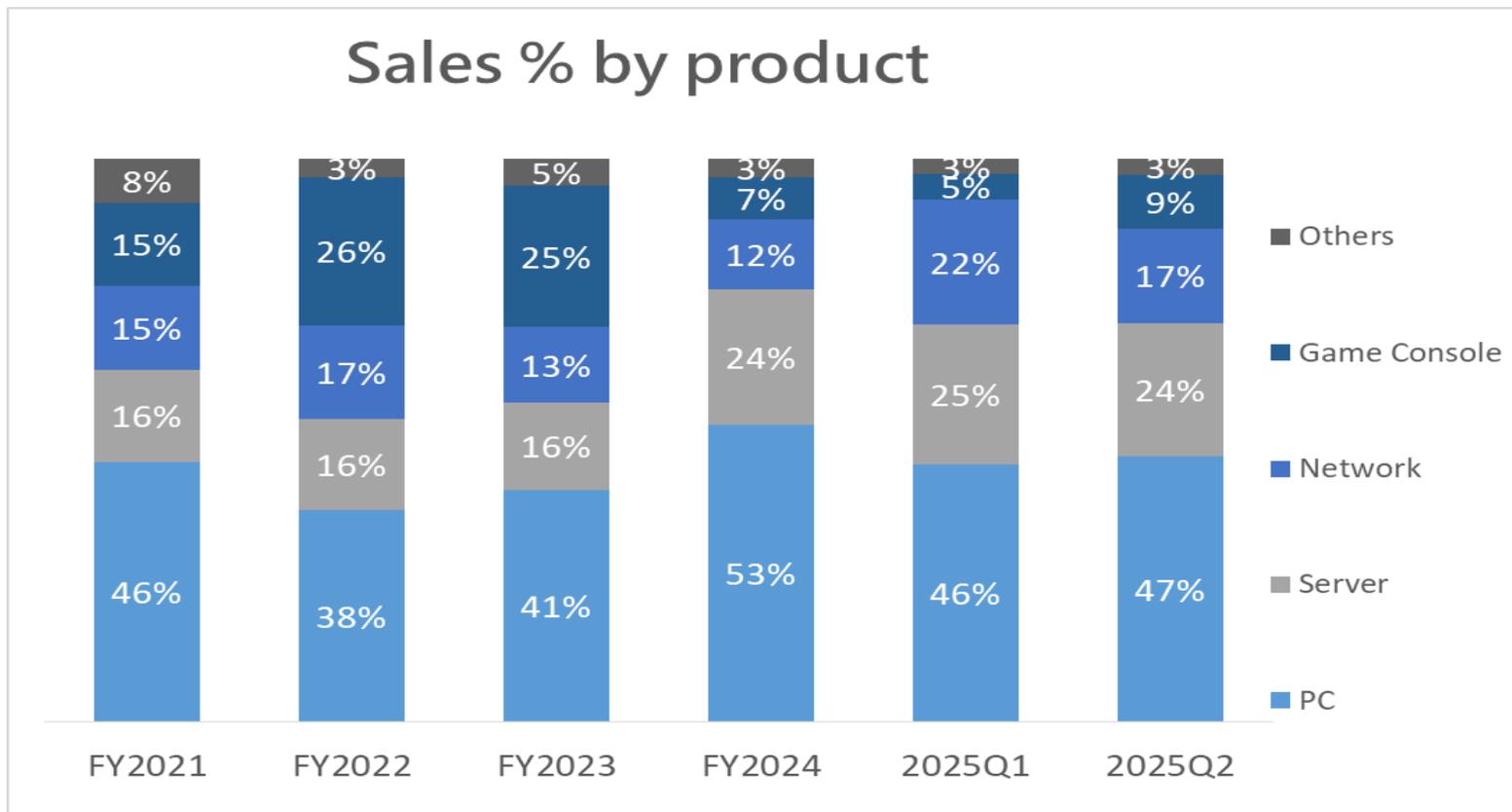
Market-Oriented Portfolio & Customization

Our products cover from 10W notebooks to 10kW AI server. We mass produce Slim VC, 3D VC, ultra-long pipes, and large-diameter pipes. Our roadmap is aligned with AI, HPC, and server market growth.

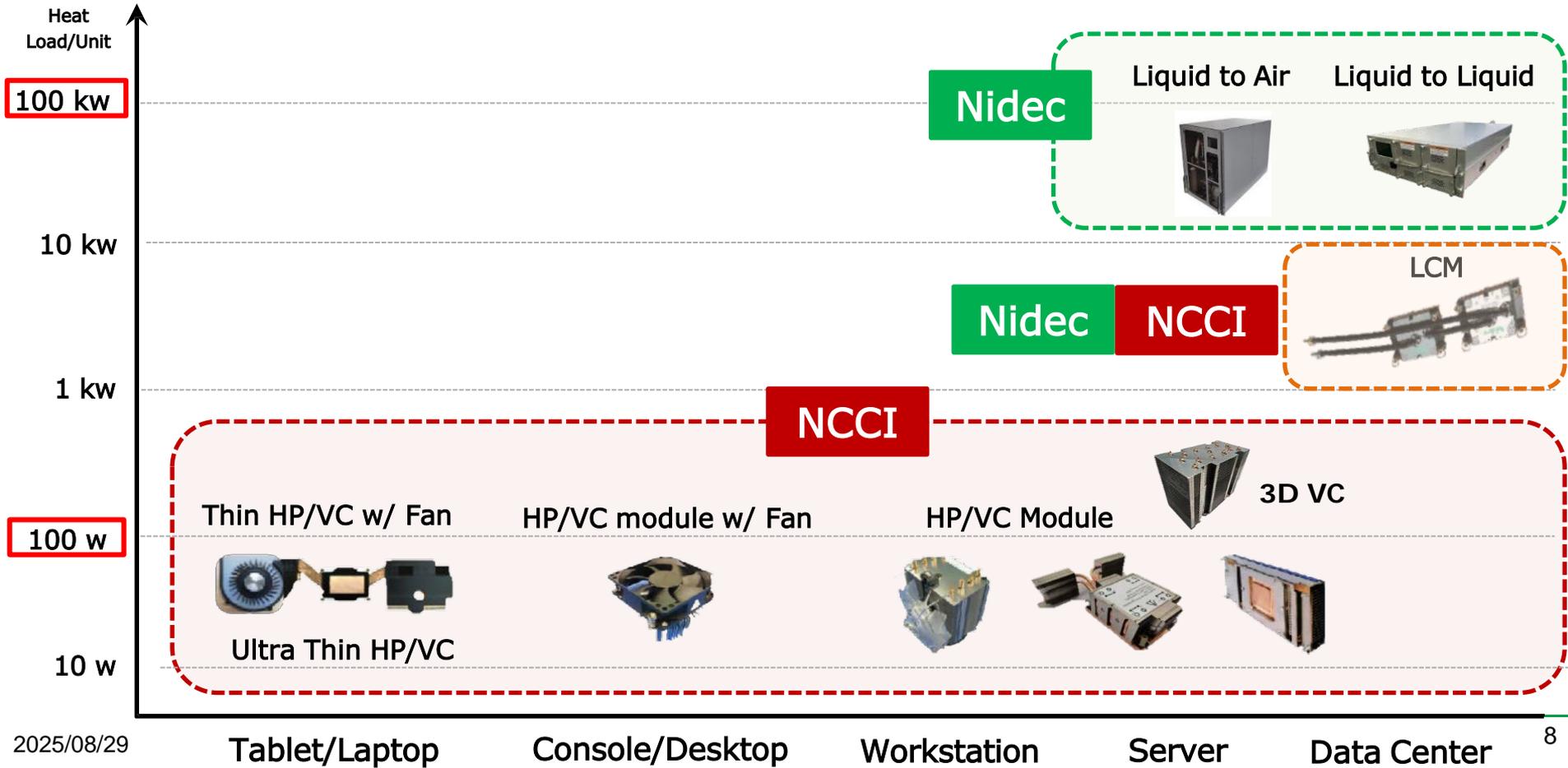
Focus Market



Business Performance



NCCI Product Line-up for Thermal Solutions



Application : Notebook/Desktop PC

Now



Thermal Solution for AI Laptop
D6/D8 Heat pipe Solution CPU+GPU 25~60 Watts



Thermal Solution for Gaming Laptop
Slim VC (1.4mm ≤ t ≤ 2.5mm) CPU+GPU 90~220 Watts



Thermal Solution for AIO & Desk Top Laptop
D6/D8 Heat pipe Solution CPU+GPU 35~65 Watts



AI人工智慧產品



Big diameter Heat pipe for CPU & GPU

Heat pipe diameter : 6mm → 10mm

Slim VC Solution for CPU & GPU

VC thickness : 1.4mm → 1.2mm

Big diameter Heat pipe for CPU & GPU

Heat pipe diameter : 8mm → 12mm

Future



Thermal Solution for AI Laptop
D10 Heat pipe Solution CPU+GPU 25~80 Watts



Thermal Solution for Gaming Laptop
Slim VC (1.2mm ≤ t ≤ 3.0mm) CPU+GPU 90~280 Watts



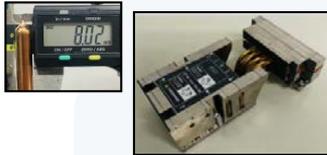
Thermal Solution for AIO & Desk Top Laptop
D10/D12 Heat pipe Solution CPU+GPU 35~95 Watts



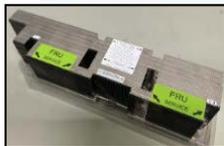
Now



One CPU solution: 500W
Heat pipe length < 400mm



D8 Heat pipe, CPU < 600W



GPU = 700W

Long Heat pipe for Cloud Server

CPU solution : 500W → 1000W
Heat pipe length : 400mm → 600mm

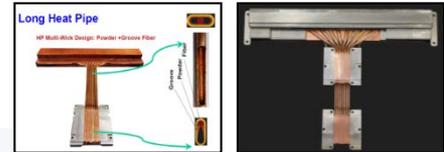
Big diameter Heat pipe for Next generation server CPU

CPU solution : 600W → 700W
Heat pipe diameter : 8mm → 10mm

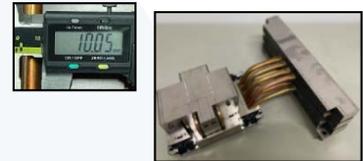
Hi-Power 3D VC Thermal Solution for AI Server

High power : 700W → 1000W

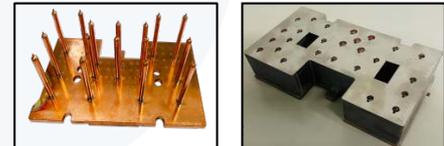
Future



Two CPU solution : Total 1000W
Heat pipe length > 600mm



D10 Heat pipe, CPU > 700W

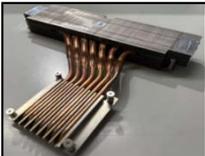


GPU > 1200W

Now



430 W HP solution



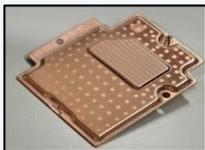
500 W HP solution

Hi-Power Air Cooling Solution for Switch

Heatpipe/VC module : 400W → 850W



103 W



152 W

VC Solution for Radio Base Station Product

VC : 100W → 255W



13 W

VC Solution for Network Card

VC : 10W → 25W

Future



850 W VC solution

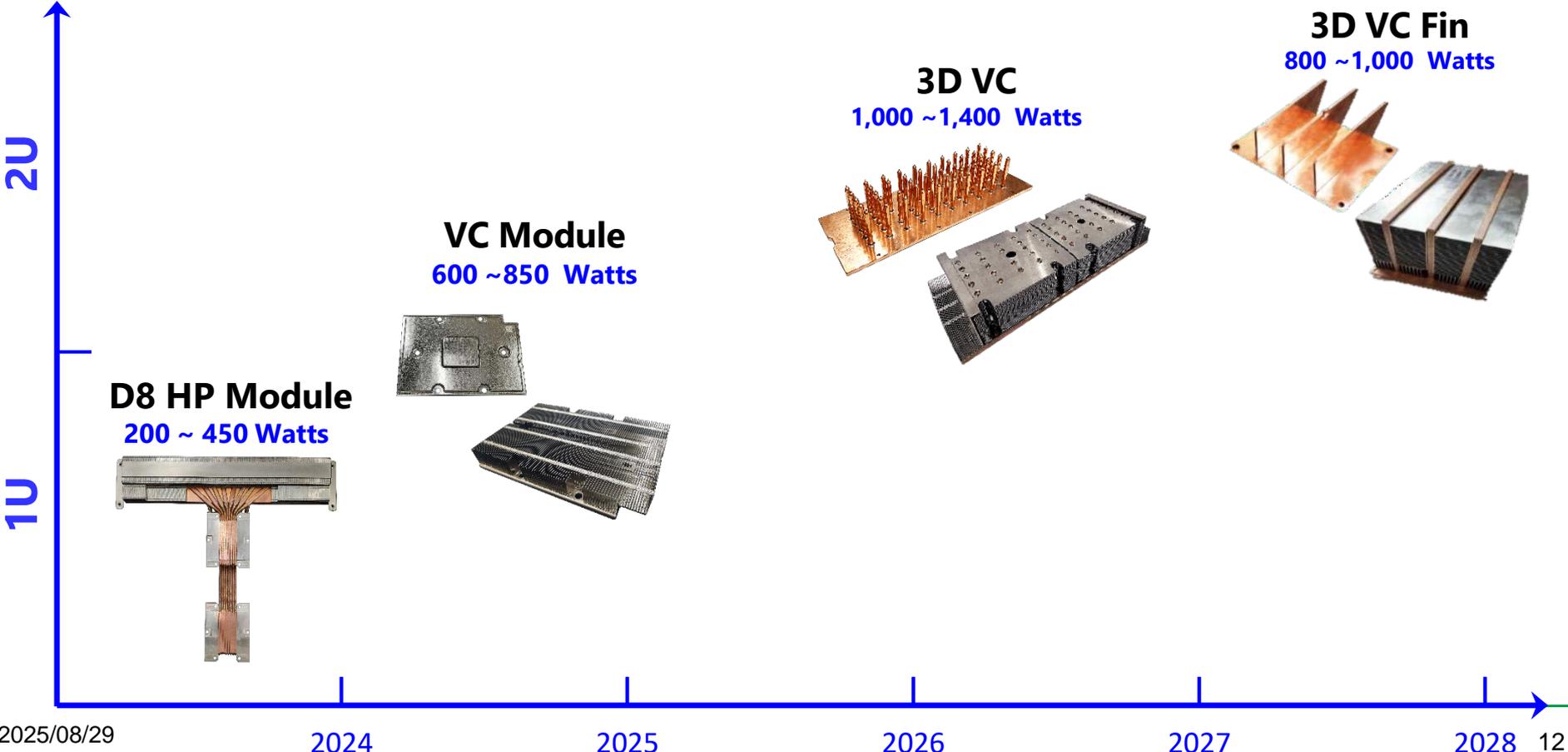


225 W



23 W

NCCI High Power Thermal Solution Roadmap(A/C)



GPU & CPU LCM Engineering Testing Fixture



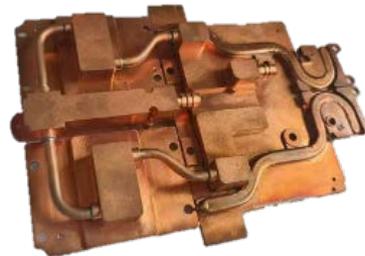
Inner Manifold



CPU LCM & Standard Cold plate

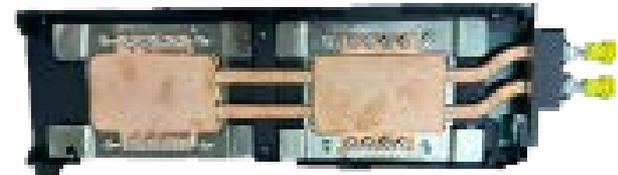


CPU LCM

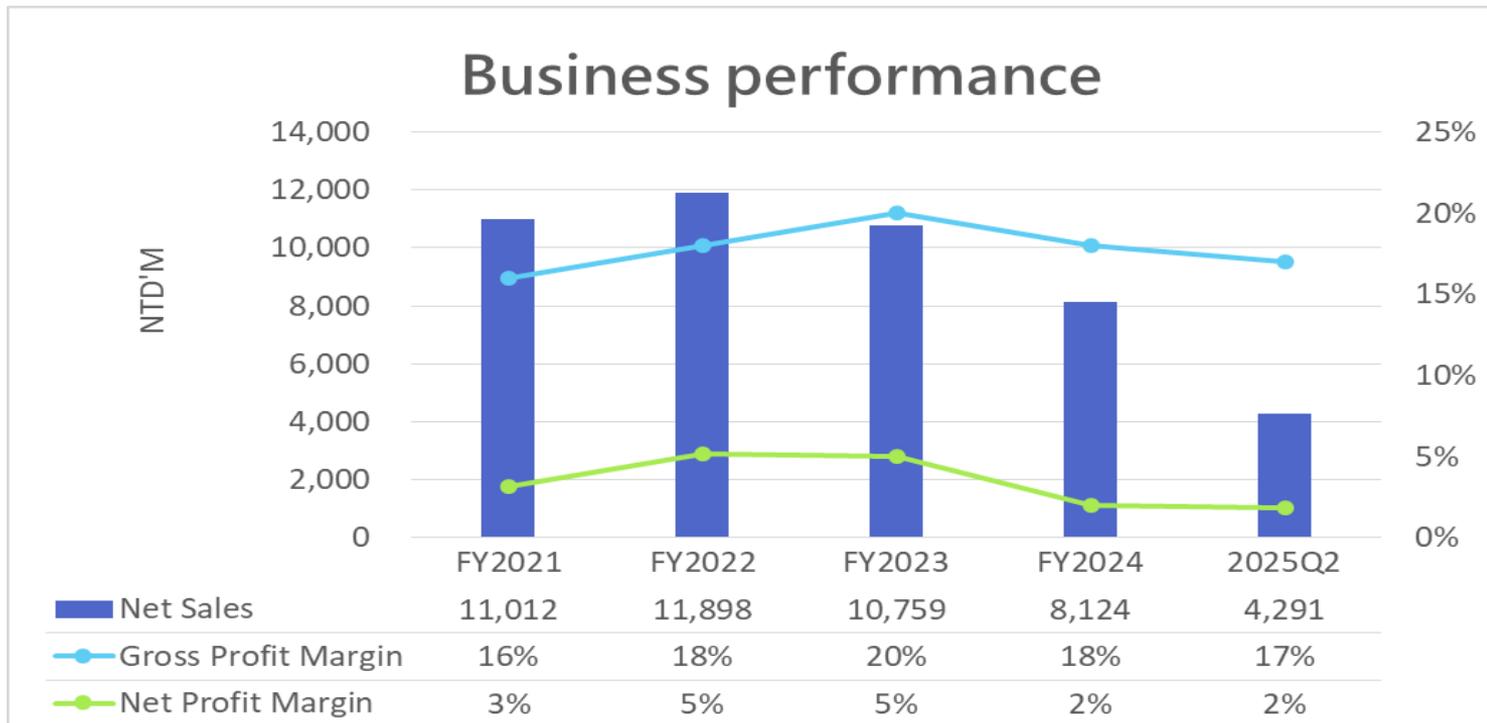


Intel CPU		AMD CPU
EGS 350W  <ul style="list-style-type: none"> • R : 0.027°C/W • ΔP: 2.77kPa 	BHS SP 350W  <ul style="list-style-type: none"> • R : 0.031°C/W • 2.75 kPa 	Milan SP3 225W  <ul style="list-style-type: none"> • R : 0.032°C/W • ΔP: 3.22 kPa
Whitley 280W  <ul style="list-style-type: none"> • R : 0.039°C/W • ΔP: 2.95 kPa 	BHS AP 500W  <ul style="list-style-type: none"> • R : 0.024°C/W • ΔP: 3.42 kPa 	Genoa SP5 500W  <ul style="list-style-type: none"> • R : 0.025°C/W • ΔP: 2.75 kPa

ASIC & PCIE LCM



Business Performance



FY NTD	2021	2022	2023	2024	2025Q2
EPS	4.05	7.10	7.02	1.48	0.80

Q & A

